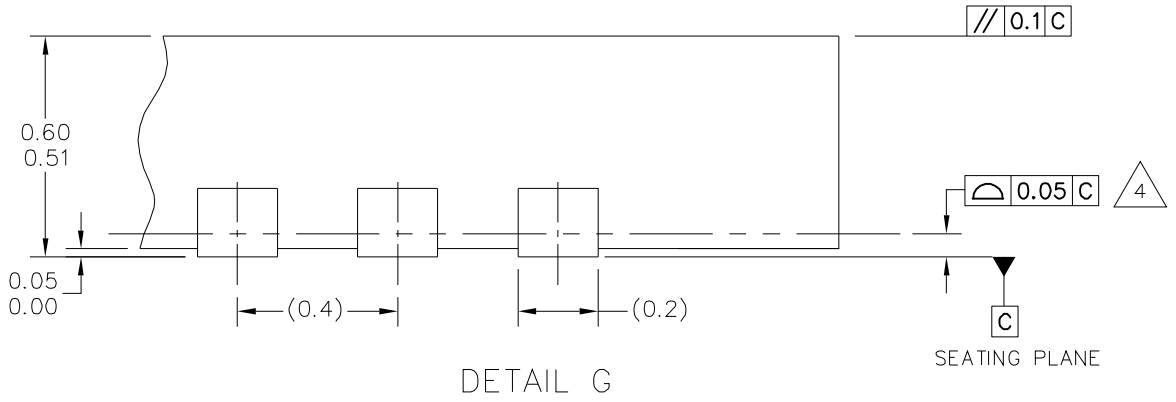



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TITLE: QUAD FLAT NO LEAD COL PACKAGE (QFN-COL) 20 TERMINAL, 0.4 PITCH (3 X 3 X 0.6)	DOCUMENT NO: 98ASA00021D	REV: A
	STANDARD: NON JEDEC	
	SOT1675-1	05 JAN 2016



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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THIS IS NON JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND ALL OTHR BOTTOM SURFACE METALLIZATION.
5. MIN. METAL GAP SHOULD BE 0.2MM.

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